

87. (New) A microelectronic package according to Claim 44 wherein the first microelectronic substrate comprises an integrated circuit and wherein the second microelectronic substrate also comprises an integrated circuit.

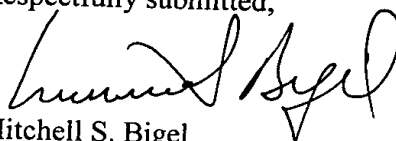
88. (New) A microelectronic package according to Claim 52 wherein the first microelectronic substrate comprises an integrated circuit and wherein the second microelectronic substrate also comprises an integrated circuit.

89. (New) A microelectronic package according to Claim 65 wherein the first microelectronic substrate comprises an integrated circuit and wherein the second microelectronic substrate also comprises an integrated circuit.

REMARKS

The present Preliminary Amendment is being filed to add Claims 78-89, which are all dependent claims that depend from the pending independent claims. Entry of the present Preliminary Amendment, and favorable examination and allowance of the present application is respectfully requested.

Respectfully submitted,



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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, Washington, DC 20231, on February 19, 2003.



Susan E. Freedman

Date of Signature: February 19, 2003